

SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

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PINNING

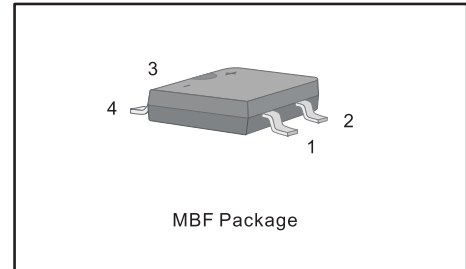
FEATURES:

- "Glass Passivated Chip Junction
- " Reverse Voltage - 100 to 1000 V
- " Forward Current - 0.8 A
- "Fast reverse recovery time
- " Designed for Surface Mount Application

PIN	DESCRIPTION
1	Input PinI~L
2	Input PinI~L
3	Output AnodeI+L
4	Output CathodeI-L

MECHANICAL DATA

- " Case: MBF
- " Terminals: Solderable per MIL-STD-750, Method 2026
- " Approx. Weight: 75mg 00026oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMB1F	FMB2F	FMB4F	FMB6F	FMB8F	FMB10F	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^\circ\text{C}$	I_O	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Maximum Forward Voltage at 0.8 A	V_F	1.3						V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5.0 50						%A
Typical Junction CapacitanceI Note1L	C_j	12						pF
Maximum Reverse Recovery Time I Note2L	t_{rr} $t_{rr(TYP.)}$	500 300						ns
Typical Thermal ResistanceI Note3L	R_{JA} R_{JC}	90 30						$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

3. Mounted on glass epoxy PC board with 4×1.5"×1.5" 3.B1 3×81 cm copper pad.

Fig.1 Average Rectified Output Current Derating Curve

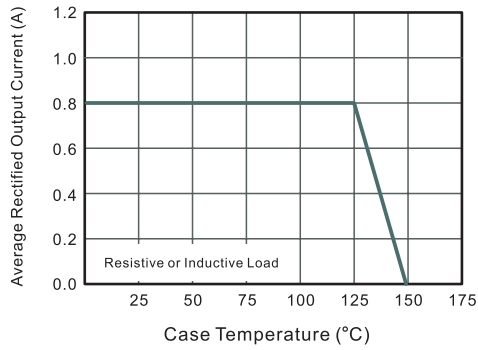


Fig.2 Typical Reverse Characteristics

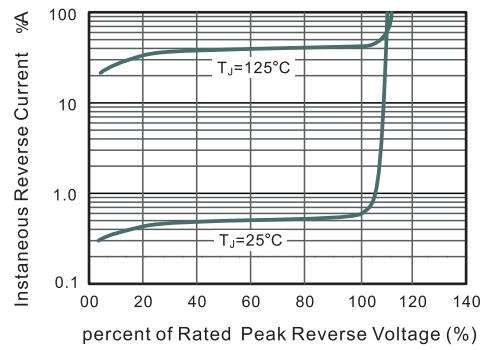


Fig.3 Typical Instantaneous Forward Characteristics

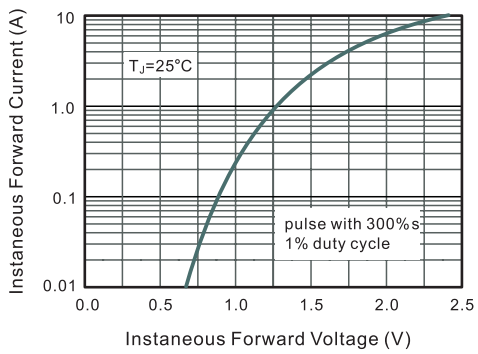


Fig.4 Typical Junction Capacitance

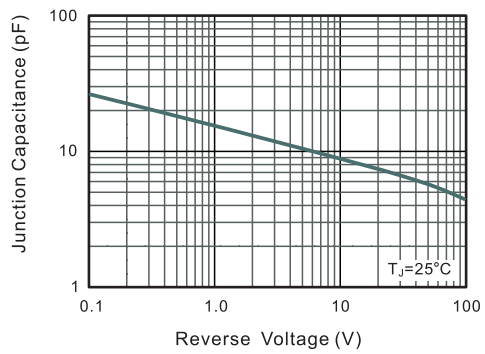
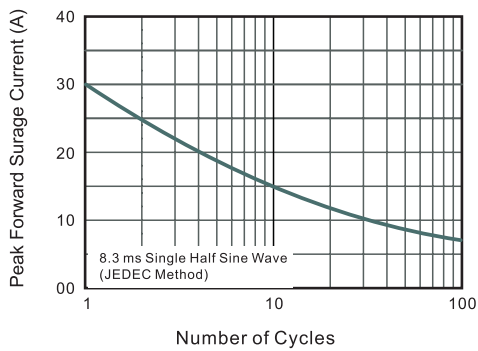


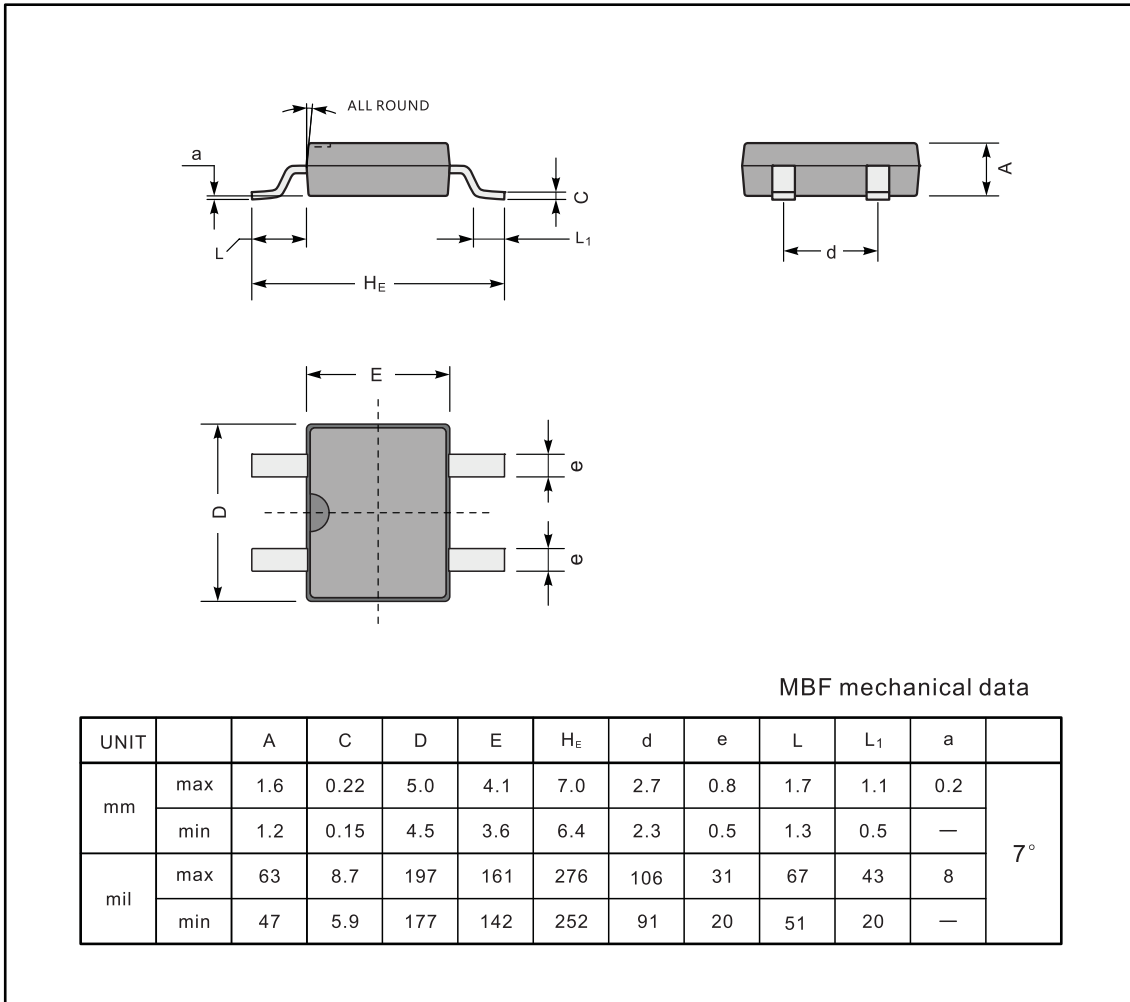
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



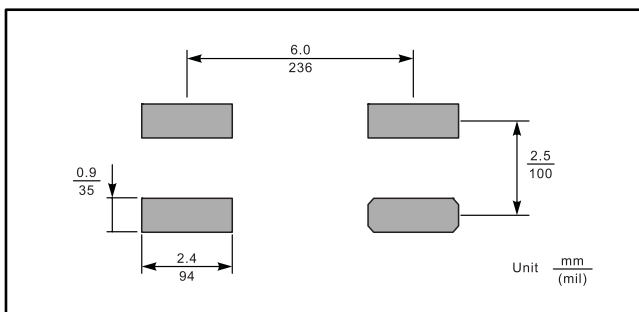
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF



The recommended mounting pad size



Marking

Type number	Marking code
FMB1F	FMB1F
FMB2F	FMB2F
FMB4F	FMB4F
FMB6F	FMB6F
FMB8F	FMB8F
FMB10F	FMB10F

